

What is claimed is:

1. A converter module having a positive terminal (2), a negative terminal (4), and a phase terminal (3), as well as a first semiconductor chip (9) and a second semiconductor chip (9), in which the terminals (2-4) and the semiconductor chips (9) are situated on top of one another in a stack,

wherein at least one of the terminals (2-4) is made up of a contact plate (5), including a bar-shaped terminal lug (6) which is positioned asymmetrically on the contact plate (5), and an auxiliary element (7) which prevents the terminal (2-4) from tilting about the longitudinal axis of the terminal lug (6), the auxiliary element (7) being able to be detached after the converter module (1) is assembled.

2. The converter module as recited in Claim 1,

wherein the phase terminal (3) is configured identically to the positive terminal (2) or the negative terminal (4).

3. The converter module as recited in Claim 1 or Claim 2,

wherein the bar-shaped terminal lug (6) is situated offset with respect to a plane created by the contact plate (5).

4. The converter module as recited in Claim 3,

wherein the bar-shaped terminal lug (6) is situated offset in such a way that, when identical terminal parts (5-7) are used for the positive terminal (2) or the negative terminal (4), and the phase terminal (3), the terminal lugs (6) may be brought out from the converter module (1) on the same level.

5. The converter module as recited in one of the preceding claims,

wherein the converter module (1) is situated in a plastic housing (12) which has been manufactured in an injection molding process.

6. The converter module as recited in one of the preceding claims,

wherein the auxiliary element (7) has a positioning aperture (11) for positioning the auxiliary element (7) in a joining device.

7. A line of multiple single-phase converter modules (1) as recited in one of the preceding claims, each having a plastic injection-molded housing (12), wherein the housings (12) are connected to one another via connecting means (13).

8. A method for manufacturing a converter module (1) having a positive terminal (2), a negative terminal (4), and a phase terminal (3), as well as a first semiconductor chip (9), and a second semiconductor chip (9), the terminals (2-4) and the semiconductor chips (9) being situated on top of one another in a stack in a joining device, wherein the positive terminal (2) or negative terminal (4), and the phase terminal (3) have a contact plate (5), including a bar-shaped terminal lug (6) which is positioned asymmetrically on the contact plate (5), and an auxiliary element (7) which prevents the terminal (2-4) from tilting about the longitudinal axis of the bar-shaped terminal lug (6); and the terminals (2-4) and the semiconductor chips (9) are placed in the joining device stacked on top of one another, the positive terminal (2) or the negative terminal (4), and the phase terminal (3) being situated rotated by 180° about the longitudinal axis of the terminal lug (6); and the stack system created in this way is encapsulated by an injection-molded plastic housing (12).

9. The method as recited in Claim 8, wherein at least one of the terminals (2-4) is positioned in the joining device using an aperture provided in the auxiliary element (7).

10. The method as recited in Claim 8, wherein the positive terminal (2) or the negative terminal (4) and the phase terminal (3) are identical parts which are inserted into the joining device rotated by 180°.